


# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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## Title of Invention

ANOLYTE FOR COPPER PLATING

Application Number : 10/616044 

Confirmation Number: 9799

First Named Applicant: Michael Yang

Attorney Docket Number: APPM/7669P2

Art Unit: 1753

Examiner: Ms. Luan V. Van

Search string: ( 6251255 or 6964792 or 6558518 or 20020195352 or 20020011415 or 20020189950 or 20010032788 or 20040016636 or 20040209414 ).pn

## US Patent Documents

**Note: Applicant is not required to submit a paper copy of cited US Patent Documents**

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6251255	2001-06-26	Copping			
	2	6964792	2005-11-15	Mayer			
	3	6558518	2003-05-06	Sendai			

## US Published Applications

**Note: Applicant is not required to submit a paper copy of cited US Published Applications**

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20020195352	2002-12-26	Mayer			
	2	20020011415	2002-01-31	Hey			
	3	20020189950	2002-12-19	Genders			
	4	20010032788	2001-10-25	Woodruff			
	5	20040016636	2004-01-29	Yang			
	6	20040209414	2004-10-21	Mok			

## Signature

Examiner Name	Date